

FEATURES

Low Profile Surface Mount
Low PIM
Low VSWR
Ideal For Automated Assembly

APPLICATIONS

Mobile Networks
Broadcast
High Power Amplifiers
Instrumentation
Isolators



GENERAL DESCRIPTION

EMC Technology's surface mount terminations are designed for direct installation on printed circuit boards and manufactured using thick film technology. Edge metallization on two sides forms the solder fillets for stronger attachment, easier inspection, and increased heat removal area. The Low PIM versions of our surface mount terminations are ideal for 4G systems and improve receiver sensitivity and overall system PIM performance.

SPECIFICATIONS

1.0 ELECTRICAL

Nominal Impedance: 50 Ω
Frequency Range: DC – 3.0 GHz
VSWR: 1.25:1 Max
Temperature Coefficient: ± 200 PPM/ $^{\circ}$ C Max
Power Rating: 4 Watts (Derating Chart)
Operating Temperature: -55 $^{\circ}$ C To +125 $^{\circ}$ C
DC Resistance: 50 $\Omega \pm 5\%$
PIM: -154 dBc, 2 Tones at 24 dBm each, 1900 MHz

2.0 MECHANICAL

Substrate: Alumina
Resistive Film: Thin Film
Metallization: Thick Film, Silver Plated

3.0 UNIT MARKING

Input Dot

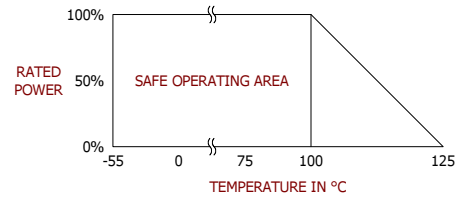
4.0 PACKAGING

Standard: Tape and Reel
Optional: Available Upon Request

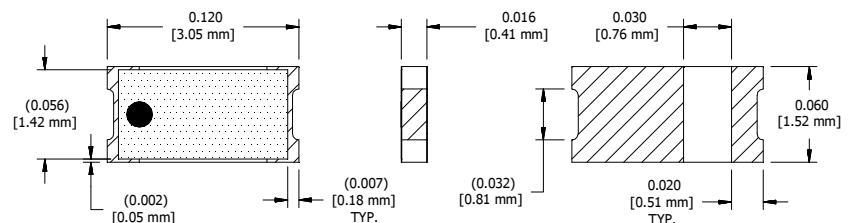
5.0 PART NUMBERING

Part Identifier: SMT1206APF

POWER RATING AND DERATING



MECHANICAL OUTLINE



Unless otherwise specified: TOLERANCE: $\pm .010$

* Note: Specifications are subject to change without notice.

**NOTE: Power handling may vary depending on mounting and heat sinking method.